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Yuri KOKOTOV et al.

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	5,208,765	05/04/93	Turnbull			07/20/90
	5,220,517	06/15/93	Sierk et al.			08/31/90
	5,226,118	07/06/93	Baker et al.		-	01/29/91
	5,231,585	07/27/93	Kobayashi et al.			06/20/90
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ATTY, DOCKET NO. SERIAL NO. INFORMATION DISCLOSURE 006365 USA/MTCG/PCTRL 10/712,273 CITATION IN AN APPLICATION (PTO-1449) APPLICANT Yuri KOKOTOV et al. FILING DATE GROUP November 14, 2003 **U.S. PATENT DOCUMENTS EXAMINER'S** FILING INITIALS PATENT NO. DATE NAME **CLASS SUBCLASS** DATE 5,270,222 12/14/93 Moslehi 12/31/90 5,283,141 02/01/94 Yoon et al. 03/05/92 5,295,242 03/15/94 Mashruwala et al. 11/02/90 5,309,221 05/03/94 Fischer et al. 12/31/91 5,329,463 07/12/94 Sierk et al. 01/13/93 5,338,630 08/16/94 Yoon et al. 11/18/93 5,347,446 09/13/94 Iino et al. 02/10/92 5,367,624 11/22/94 Cooper 06/11/93. 5,375,064 12/20/94 Bollinger 12/02/93 5,398,336 03/14/95 Tantry et al. 06/16/93 5,408,405 04/18/95 Mozumder et al. 09/20/93 5,410,473 04/25/95 Kaneko et al. 12/16/92 5,420,796 05/30/95 Weling et al. 12/23/93 5,427,878 06/27/95 Corliss 05/16/94 5,469,361 11/21/95 Moyne 06/06/94 5,485,082 01/16/96 Wisspeintner et al. 04/05/90 5,490,097 02/06/96 Swenson et al. 08/06/93 5,495,417 02/27/96 Fuduka et al. 03/16/93 5,497,316 03/05/96 Sierk et al. 04/04/95 5,497,381 03/05/96 O'Donoghue et al. 06/01/95 5,503,707 04/02/96 Maung et al. 09/22/93 5,508,947 04/16/96 Sierk et al. 05/13/94 5,511,005 04/23/96 Abbe et al. 02/16/94 5,525,808 06/11/96 Irie et al. 12/20/94 5,526,293 06/11/96 Mozumder et al. 12/17/93 5,534,289 07/09/96 Bilder et al. 01/03/95 5,541,510 07/30/96 Danielson 04/06/95 **EXAMINER DATE CONSIDERED** 00

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INF	ORMATION		SURE	ATTY. DOCKET NO. 006365 USA/MTCG/PCTRL		SERIAL NO.	
	CITATIO	N IN AN		000303 OSAMIC	JIFCIKL	10/712,27	13
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INITIALS	PATENT NO.	DATE		NAME	CLASS	SUBCLASS	DATE
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	5,599,423	02/04/97	Parker et al.				06/30/95
	5,602,492	02/11/97	Cresswell et al.				04/28/94
	5,603,707	02/18/97	Trombetta et al	•			11/28/95
	5,617,023	04/01/97	Skalski			 	02/02/95
	5,627,083	05/06/97	Tounai		<u> </u>		05/12/95
	5,629,216	05/13/97	Wijaranakula e	t al.			02/27/96
	5,642,296	06/24/97	Saxena	•			07/29/93
	5,646,870	07/08/97	Krivokapic et a	1.			02/13/95
	5,649,169	07/15/97	Berezin et al.	·			06/20/95
	5,655,951	08/12/97	Meikle et al.	11		···	09/29/95
	5,657,254	08/12/97	Sierk et al.	· ***		***	04/15/96
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	5,663,797	09/02/97	Sandhu				05/16/96
	5,664,987	09/09/97	Renteln				09/04/96
	5,665,199	09/09/97	Sahota et al.	· · · · · · · · · · · · · · · · · · ·	i		06/23/95
	5,667,424	09/16/97	Pan				09/25/96
	5,674,787	10/07/97	Zhao et al.				01/16/96
	5,694,325	12/02/97	Fukuda et al.				11/22/95
	5,698,989	12/16/97	Nulman				09/13/96
\	5,719,495	02/17/98	Moslehi				06/05/96
	5,719,796	02/17/98	Chen			-	12/04/95
	5,735,055	04/07/98	Hochbein et al.	<u> </u>			04/23/96
مالك	5,740,429	04/14/98	Wang et al.				07/07/95
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INF	ORMATION	N DISCLOS	SURE	ATTY. DOCKET NO. SERIAL NO. 10/712.273			
	CITATIO	N IN AN		UU0363 USA/MTCC	J/PCTRL	10/712,27	/3
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EXAMINER'S					· · ·	<u> </u>	FILING
INITIALS	PATENT NO.	DATE	ļ	NAME	CLASS	SUBCLASS	DATE
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	5,754,297	05/19/98	Nulman				04/14/97
	5,761,064	06/02/98	La et al.	·			10/06/95
	5,761,065	06/02/98	Kittler et al.				03/30/95
	5,764,543	06/09/98	Kennedy				06/16/95
7	5,777,901	07/07/98	Berezin et al.				09/29/95
	5,787,021	07/28/98	Samaha				12/18/95
	5,787,269	07/28/98	Hyodo		-	·	09/19/95
\ .	5,808,303	09/15/98	Schlagheck et	al.			01/29/97
	5,812,407	09/22/98	Sato et al.				08/12/97
	5,823,854	10/20/98	Chen	···			05/28/96
	5,828,778	10/27/98	Hagi et al.	-			07/12/96
 	5,832,224	11/03/98	Fehskens et al.				06/14/96
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	5,859,964	01/12/99	Wang et al.				10/25/96
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	5,862,054	01/19/99	Li	· · · · · · · · · · · · · · · · · · ·			02/20/97
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	5,867,389	02/02/99	Hamada et al.				11/26/96
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- 	5,903,455	05/11/99	Sharpe, Jr. et a				12/12/96
- - 	5,910,011	06/08/99	Cruse	··			
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INFORMATION DISCLOSURE			ATTY. DOCKET NO. SERIAL NO. 006365 USA/MTCG/PCTRL 10/712.273				
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INITIALS	PATENT NO.	DATE		NAME	CLASS	SUBCLASS	DATE
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	6,136,163	10/24/00	Cheung et al.				03/05/99
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INFORMATION DISCLOSURE ATTY, DOCKET NO. SERIAL NO. 006365 USA/MTCG/PCTRL 10/712,273 CITATION IN AN APPLICATION (PTO-1449) APPLICANT Yuri KOKOTOV et al. FILING DATE GROUP November 14, 2003 U.S. PATENT DOCUMENTS **EXAMINER'S** FILING INITIALS PATENT NO. DATE NAME CLASS **SUBCLASS** DATE 6,226,792 B1 05/01/01 Goiffon et al. 10/14/98 6,230,069 B1 05/08/01 Campbell et al. 06/26/98 05/22/01 6,236,903 B1 Kim et al. 09/25/98 2001/0001755 A1 05/24/01 Sandhu et al. 12/29/00 6,240,330 B1 Kurtzberg et al. 05/29/01 05/28/97 6,240,331 B1 05/29/01 Yun 08/18/98 2001/0003084 A1 06/07/01 Finarov 12/04/00 6,245,581 B1 06/12/01 Bonser et al. 04/19/00 6,248,602 B1 06/19/01 Bode et al. 11/01/99 6,249,712 B1 06/19/01 Boiquaye 09/25/96 6,252,412 B1 06/26/01 Talbot et al. 01/08/99 6,253,366 B1 06/26/01 Mutschler, III 03/31/99 6,263,255 B1 07/17/01 Tan et al. 05/18/98 6,271,670 B1 08/07/01 Caffey 02/08/99 6,276,989 B1 08/21/01 Campbell et al. 08/11/99 08/21/01 6,278,899 B1 Piche et al. 10/06/98 6,280,289 B1 08/28/01 Wiswesser et al. 11/02/98 6,284,622 B1 09/04/01 Campbell et al. 10/25/99 6,287,879 B1 09/11/01 Gonzales et al. 08/11/99 6,290,572 B1 09/18/01 Hofmann 03/23/00 6,292,708 B1 09/18/01 Allen et al. 06/11/98 6,298,274 B1 10/02/01 Inoue 09/01/99 6,298,470 B1 10/02/01 Breiner et al. 04/15/99 6,303,395 B1 10/16/01 Nulman 06/01/99 6,304,999 B1 10/16/01 Toprac et al. 10/23/00 2001/0030366 A1 10/18/01 Nakano et al. 03/07/01 6,307,628 B1 10/23/01 Lu et al. 08/18/00 6,314,379 B1 11/06/01 Hu et al. 12/04/97 **EXAMINER** DATE CONSIDERED 11/11/06

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				Yuri KOKOTOV	et al.		
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ATTY. DOCKET NO. INFORMATION DISCLOSURE SERIAL NO. 006365 USA/MTCG/PCTRL 10/712,273 CITATION IN AN **APPLICATION** (PTO-1449) APPLICANT Yuri KOKOTOV et al. FILING DATE GROUP November 14, 2003 **U.S. PATENT DOCUMENTS EXAMINER'S** FILING INITIALS PATENT NO. DATE NAME **CLASS** SUBCLASS DATE \mathcal{L} 6,503,839 B2. 01/07/03 Gonzales et al. 07/03/01 2003/0020909 A1 01/30/03 Adams et al. 04/09/01 2003/0020928 A1 01/30/03 Ritzdorf et al. 07/09/01 6,517,413 B1 02/11/03 Hu et al. 10/25/00 6,540,591 B1 04/01/03 Pasadyn et al. 04/18/01 6,560,504 B1 05/06/03 Goodwin et al. 09/29/99 6,563,308 B2 05/13/03 Nagano et al. 03/27/01 6,567,717 B2 05/20/03 Krivokapic et al. 01/19/00 6,587,744 B1 07/01/03 Stoddard et al. 06/20/00 6,590,179 B2 07/08/03 Tanaka et al. 02/26/01 6,604,012 B1 08/05/03 Cho et al. 08/23/00 6,618,692 B2 09/09/03 Takahashi et al. 02/26/01 6,625,497 B2 09/23/03 Fairbairn et al. 07/10/01 6,640,151 B1 10/28/03 Somekh et al. 12/22/99 **EXAMINER** DATE CONSIDERED

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	00444.5.5	1004655		Medium			
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	1			Manufacturing Facility Service Reque	estors		
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